



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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LEAD-FREE P/N

85995-X03LF

17.55 MAX.

PLATING CODE X

PLATING CONTACT AREA

1

1.3  $\mu\text{m}$  Au MIN

2.4 MAX

9 REF.

2.22 MIN

2.5 REF.

2.5 MIN

11.4 REF.

8.4 REF.

3.2 MAX

 $\phi 4.8$ 

4.75 MAX.

5.25 REF.

5 REF.

5.7 REF.

CONTACT AREA

0.3 REF.

6 MAX.

5 REF.

0.6 REF.

## NOTES:

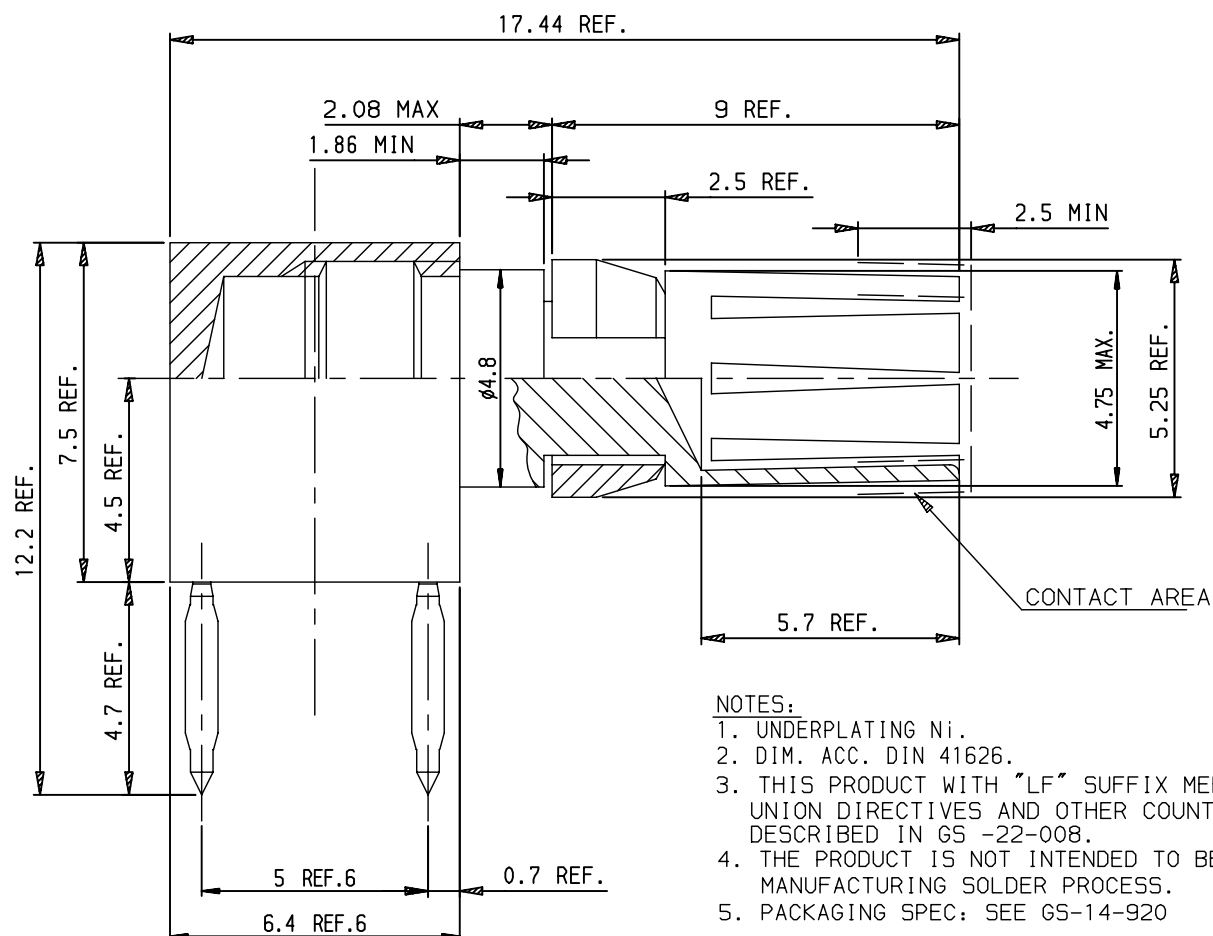
1. UNDERPLATING Ni.
2. DIM. ACC. DIN 41626.
3. THIS PRODUCT WITH "LF" SUFFIX MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS -22-008.
4. THE PRODUCT WILL WITHSTAND EXPOSURE TO 260 DEGREE PEAK TEMPERATURE TO 30 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6 mm MINIMUM THICK PCB
5. PACKAGING SPEC: SEE GS-14-920

European Views

www.fciconnect.com		surface ISO 1302	tolerance std ISO 406 ISO 1101		projection mm	size A3		Scale 10
		TOLERANCES UNLESS OTHERWISE SPECIFIED						
Dr	GOISNARD	2006/03/06	ANGULAR	LINEAR	0.X	$\pm 0.1$	size	ECN
Eng	GOISNARD	2006/03/06	0.XX		0.XX	$\pm 0.1$	A3	LS08-0057
Chr	LEGARE	2006/03/06	0.XX' $\pm 2$		0.XXX	$\pm 0.1$	ECN	LS08-0057
Appr	LEGARE	2006/03/06	Product family		METRAL		Spec ref -	
FCI		POWER INSERT		title		dwg no		Rev.
		RECEPTACLE RA STB				85995		G
catalog no				CUSTOMER		sheet 1 of 2		




rev	ecn no	dr	date
E	LS06-0022	LGO	2006/03/06
F	LS07-0214	LGO	2007/08/21
G	LS08-0057	LGO	2008/02/18
-	-	-	-
-	-	-	-
-	-	-	-
-	-	-	-

PLATING CODE X	CONTACT AREA
1	1.3 $\mu\text{m}$ Au MIN



1. UNDERPLATING Ni.
2. DIM. ACC. DIN 41626.
3. THIS PRODUCT WITH "LF" SUFFIX MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS -22-008.
4. THE PRODUCT IS NOT INTENDED TO BE EXPOSED TO A MANUFACTURING SOLDER PROCESS.
5. PACKAGING SPEC: SEE GS-14-920

## European Views

www.fciconnect.com			surface ISO 1302 ✓		tolerance std ISO 406 ISO 1101		projection 		mm 	
			TOLERANCES UNLESS OTHERWISE SPECIFIED							
Dr	GOISNARD	2006/03/06	ANGULAR	LINEAR	0.X	±0.1	size A3	Scale 9		
Eng	GOISNARD	2006/03/06			0.XX	±0.1				
Chr	LEGARE	2006/03/06			0.XXX	±0.1		ECN LS08-0057		
Appr	LEGARE	2006/03/06	Product family METRAL				Spec ref -			
	POWER INSERT					dwg no 85995			Rev. G	
	RECEPTACLE RA STB									
catalog no			-			CUSTOMER		sheet 2 of 2		